

NAND Flash PHY Units for Advanced SSD Design

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- 2-Plane NAND Technology is hitting a wall:
	- Sub 1xnm devices suffer from pronounced reliability issues
	- Simple ECC alone is no longer sufficient
	- Handling reliability issues requires a myriad of new techniques – a Memory Modem™
- Next generation products will need to be much more complex or deliver very limited reliability

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- FTL and PHY Separation?
- What does the Memory Modem™ Do?
- What does the FTL Do?
- Modular Approach
- Summary

Why separate FTL and PHY-Memory Modem™

- Time to Market:
	- NAND Flash from different vendors require very different techniques – with different overheads. Yet, FTL may remain the same
	- Different applications using same NAND need only FTL changes and no Memory Modem™ change
- Engineering Resources Management:
	- Completely different type of SW expertise
	- Modular design

PHY-Memory Modem™ Integration With FTL

- Memory Modem on Controller:
	- Clear NAND Constrained Design
	- FTL specific adaptation of PHY
	- Resource Sharing

Conventional FTL vs. Separated

Standard FLASH Controller

Controller FTL Memory Modem™ NAND Interface $\begin{vmatrix} 1 & 1 \\ 1 & 1 \end{vmatrix}$ NAND Interface Virtual NAND Interface Separated FTL - PHY approach

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FTL Point of View in a Separated System

- Virtual NAND:
	- Reliable
	- Virtual Block not necessarily same size as Physical block
	- Virtual page size may be larger than a single die page

What does the Memory Modem™ do? (1)

- Handle all reliability issues due to:
	- Endurance
	- Retention
	- Read disturbs
	- Sudden power loss
	- Different block types
	- \bullet . . .
- Optimize raw performance for given NAND Flash type and state:
	- Programming Speeds
	- Read Speeds

What does the Memory Modem™ do? (2)

- How does it do it:
	- Powerful, configurable, low power ECC (not BCH nor LPDC) which performs both hard and soft decoding
	- DSP
	- Low Level Management: Data allocation across NAND blocks and dies to optimize reliability

- Near optimal reliability close to theoretical bound
- Performs both hard and soft decoding
	- Hard decoding determines the joint reliability performance point
	- Soft decoding performance depends on sampling speeds
- Optimal and high performance hard decoding
- Low power
- Configurable: Code size, code rate, code capabilities

Memory Modem™ - DSP

- Tracks block state
- Modifies NAND trim parameters according to block state to optimize read results
- Modifies NAND trim parameters during programming to optimize reliability and performance (tProg)
- Detect different disturb factors to inform FTL:
	- Stale blocks
	- Read Disturbs
	- …
- Ungraceful power-downs:
	- Detect
	- Recover Data

Memory Modem™ - Low Level Management (1)

- Data allocation within blocks and dies can reduce the effect of worst case pages:
	- Example: TLC NAND Flash has 3 types of pages with different BERs: MSB, CSB & LSB (Lower, Middle, Upper)
	- Interleaving between MSB and LSB pages averages BERs
	- Alternatively, variable rate coding may be used

Memory Modem™ - Low Level Management (2)

- To support interleaving or coupling between pages of different types, buffering may be required:
	- Example: Buffering some of the data into SLC to allow striping / coupling between MSB pages of first rows with LSB pages of the last rows

Memory Modem™ - Low Level Management (3)

- Interleaving / Coupling / Variable rate coding schemes:
	- Highly dependent on target devices
	- Dynamic, changing depending on Flash state
	- Choice may affect buffering
- Handled by Memory-Modem, without (or hardly) involving FTL:
	- Buffering should be hidden
	- FTL is ignorant of the choice of data allocation scheme
	- Data allocation scheme may change to support different performance requirements

Memory Modem™ – Adaptive/Dynamic Behavior

- Memory modem™ dynamically tracks NAND Flash state and changes the following:
	- DSP Trim parameters during programming and reading
	- Codeword size, Codeword rates
	- Data allocation strategy: stripping, page coupling, variable rate coding

- Handle host interface
- Handle control data
- Data mapping
	- Performance optimized tables
	- De-duplication
	- Compression
	- SLC / MLC / TLC block mapping
- Encryption

- High level integrity handling:
	- Wear leveling
	- Bad block handling
	- Power-down recovery control data
	- Scrubbing
	- \bullet ……

- Each Memory Modem™ handles a set of NAND channels
- Each Module may be customizable:
	- Throughput
	- Latency
- Scalable through instantiation:
	- Higher throughputs
	- Higher IOPs
	- Higher capacities
	- Same module may be used for price sensitive embedded systems as well as enterprise SSD

Memory Modem™ Architecture (1)

- ECC Encoder
	- Streaming data operation
- ECC Decoder
	- Hard and Soft decoding
	- High performance:
	- Low latency
- DSP
	- Flexible : adaptable per Flash device
	- Mainly SW
	- Full HW acceleration of data processing

Memory Modem™ Architecture (2)

• NAND Unit

- High performance
- High NAND channel utilization
- Flexible: configurable per Flash device
- Configurable # of channels and # of dies per channel
- Control Interface FTL to PHY:
	- PHY is slave to FTL level
	- Commands are sent from FTL to PHY
	- PHY sends responses to FTL
	- Large number of outstanding commands

- Interface required to support different types of messages:
	- Block refresh required
		- Read Disturb, High Retention, High BER Indication PHY informs FTL and request block refresh
	- Recovery mode
		- PHY may indicate that entire drive has undergone retention and should be refreshed entirely
	- S.M.A.R.T

- Power down indications:
	- Regrets messages
	- Enables Power / Performance Optimization
	- Optimization of boot time
- Internal PHY NCQ:
	- FTL handles operations at PHY Module level

PHY Architecture Customization **Continued**

- PHY Module Customization :
	- Random Read Requirements \rightarrow Number of CPUs
	- Sequential Read Requirements \rightarrow Number of Channels
	- (system / die) Capacity Channel capability
	- Datapath BW Read performance Encoder/Decoder Recovery performance end of life
	- Ungraceful Power Down handling Write flow **Buffer Memory Size** Recovery flow
-
- (system / die) write bandwidth \rightarrow Max number of devices per Channel
	-

Over all PHY Performance \rightarrow number of PHY modules

- New generation of NAND Flash devices require a strong PHY
	- PHY = ECC + DSP + low level management + Flash interface
- FTL-PHY separation modular approach allows scalability and easy adaptation to different applications